



Welcome to **E-XFL.COM** 

**Understanding Embedded - CPLDs (Complex Programmable Logic Devices)** 

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

## **Applications of Embedded - CPLDs**

Details	
Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	2
Number of Macrocells	32
Number of Gates	600
Number of I/O	36
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=epm7032tc44-7

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Table 2. MAX	7000S Device I	Features -				
Feature	EPM7032S	EPM7064S	EPM7128S	EPM7160S	EPM7192S	EPM7256S
Usable gates	600	1,250	2,500	3,200	3,750	5,000
Macrocells	32	64	128	160	192	256
Logic array blocks	2	4	8	10	12	16
Maximum user I/O pins	36	68	100	104	124	164
t <sub>PD</sub> (ns)	5	5	6	6	7.5	7.5
t <sub>SU</sub> (ns)	2.9	2.9	3.4	3.4	4.1	3.9
t <sub>FSU</sub> (ns)	2.5	2.5	2.5	2.5	3	3
t <sub>CO1</sub> (ns)	3.2	3.2	4	3.9	4.7	4.7
f <sub>CNT</sub> (MHz)	175.4	175.4	147.1	149.3	125.0	128.2

## ...and More Features

- Open-drain output option in MAX 7000S devices
- Programmable macrocell flipflops with individual clear, preset, clock, and clock enable controls
- Programmable power-saving mode for a reduction of over 50% in each macrocell
- Configurable expander product-term distribution, allowing up to 32 product terms per macrocell
- 44 to 208 pins available in plastic J-lead chip carrier (PLCC), ceramic pin-grid array (PGA), plastic quad flat pack (PQFP), power quad flat pack (RQFP), and 1.0-mm thin quad flat pack (TQFP) packages
- Programmable security bit for protection of proprietary designs
- 3.3-V or 5.0-V operation
  - MultiVolt<sup>TM</sup> I/O interface operation, allowing devices to interface with 3.3-V or 5.0-V devices (MultiVolt I/O operation is not available in 44-pin packages)
  - Pin compatible with low-voltage MAX 7000A and MAX 7000B devices
- Enhanced features available in MAX 7000E and MAX 7000S devices
  - Six pin- or logic-driven output enable signals
  - Two global clock signals with optional inversion
  - Enhanced interconnect resources for improved routability
  - Fast input setup times provided by a dedicated path from I/O pin to macrocell registers
  - Programmable output slew-rate control
- Software design support and automatic place-and-route provided by Altera's development system for Windows-based PCs and Sun SPARCstation, and HP 9000 Series 700/800 workstations

The MAX 7000E devices—including the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices—have several enhanced features: additional global clocking, additional output enable controls, enhanced interconnect resources, fast input registers, and a programmable slew rate.

In-system programmable MAX 7000 devices—called MAX 7000S devices—include the EPM7032S, EPM7064S, EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices. MAX 7000S devices have the enhanced features of MAX 7000E devices as well as JTAG BST circuitry in devices with 128 or more macrocells, ISP, and an open-drain output option. See Table 4.

Table 4. MAX 7000 Device Feat	ures		
Feature	EPM7032 EPM7064 EPM7096	All MAX 7000E Devices	All MAX 7000S Devices
ISP via JTAG interface			✓
JTAG BST circuitry			<b>√</b> (1)
Open-drain output option			<b>✓</b>
Fast input registers		<b>✓</b>	✓
Six global output enables		<b>✓</b>	✓
Two global clocks		✓	✓
Slew-rate control		<b>✓</b>	<b>✓</b>
MultiVolt interface (2)	✓	<b>✓</b>	<b>✓</b>
Programmable register	✓	<b>✓</b>	✓
Parallel expanders	<b>✓</b>	✓	✓
Shared expanders	<b>✓</b>	<b>✓</b>	✓
Power-saving mode	✓	✓	✓
Security bit	✓	✓	✓
PCI-compliant devices available	✓	✓	✓

#### Notes:

- (1) Available only in EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices only.
- (2) The MultiVolt I/O interface is not available in 44-pin packages.

The MAX 7000 architecture supports 100% TTL emulation and high-density integration of SSI, MSI, and LSI logic functions. The MAX 7000 architecture easily integrates multiple devices ranging from PALs, GALs, and 22V10s to MACH and pLSI devices. MAX 7000 devices are available in a wide range of packages, including PLCC, PGA, PQFP, RQFP, and TQFP packages. See Table 5.

Table 5. M.	AX 7000	) Maxim	um Use	r I/O Pii	ıs N	ote (1)						
Device	44- Pin PLCC	44- Pin PQFP	44- Pin TQFP	68- Pin PLCC	84- Pin PLCC	100- Pin PQFP	100- Pin TQFP	160- Pin PQFP	160- Pin PGA	192- Pin PGA	208- Pin PQFP	208- Pin RQFP
EPM7032	36	36	36									
EPM7032S	36		36									
EPM7064	36		36	52	68	68						
EPM7064S	36		36		68		68					
EPM7096				52	64	76						
EPM7128E					68	84		100				
EPM7128S					68	84	84 (2)	100				
EPM7160E					64	84		104				
EPM7160S					64		84 (2)	104				
EPM7192E								124	124			
EPM7192S								124				
EPM7256E								132 (2)		164		164
EPM7256S											164 (2)	164

#### Notes:

- When the JTAG interface in MAX 7000S devices is used for either boundary-scan testing or for ISP, four I/O pins become JTAG pins.
- (2) Perform a complete thermal analysis before committing a design to this device package. For more information, see the Operating Requirements for Altera Devices Data Sheet.

MAX 7000 devices use CMOS EEPROM cells to implement logic functions. The user-configurable MAX 7000 architecture accommodates a variety of independent combinatorial and sequential logic functions. The devices can be reprogrammed for quick and efficient iterations during design development and debug cycles, and can be programmed and erased up to 100 times.

MAX 7000 devices contain from 32 to 256 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms to provide up to 32 product terms per macrocell.

The MAX 7000 family provides programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000E and MAX 7000S devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000 devices (except 44-pin devices) can be set for either 3.3-V or 5.0-V operation, allowing MAX 7000 devices to be used in mixed-voltage systems.

The MAX 7000 family is supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2 0 0 and 3 0 0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.



For more information on development tools, see the MAX+PLUS II Programmable Logic Development System & Software Data Sheet and the Quartus Programmable Logic Development System & Software Data Sheet.

# Functional Description

The MAX 7000 architecture includes the following elements:

- Logic array blocks
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable interconnect array
- I/O control blocks

The MAX 7000 architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of EPM7032, EPM7064, and EPM7096 devices.

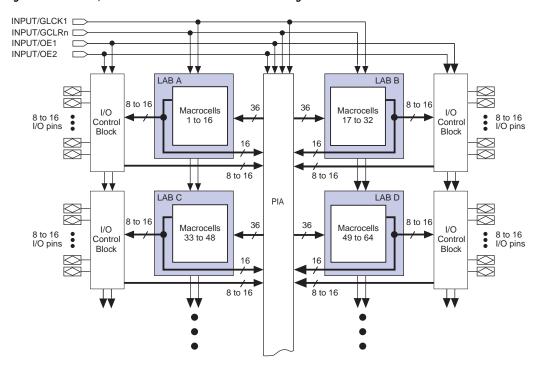


Figure 1. EPM7032, EPM7064 & EPM7096 Device Block Diagram

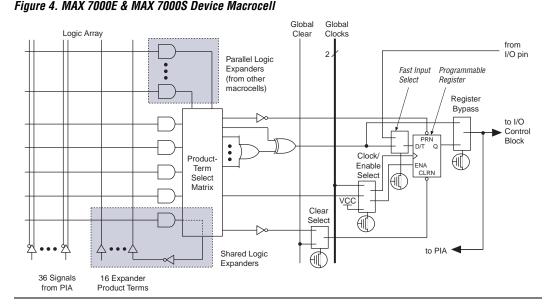


Figure 4 shows a MAX 7000E and MAX 7000S device macrocell.

Combinatorial logic is implemented in the logic array, which provides five product terms per macrocell. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as secondary inputs to the macrocell's register clear, preset, clock, and clock enable control functions. Two kinds of expander product terms ("expanders") are available to supplement macrocell logic resources:

- Shareable expanders, which are inverted product terms that are fed back into the logic array
- Parallel expanders, which are product terms borrowed from adjacent macrocells

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the Altera development software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.



For more information on using the Jam language, refer to AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor.

The ISP circuitry in MAX 7000S devices is compatible with IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

## **Programming Sequence**

During in-system programming, instructions, addresses, and data are shifted into the MAX 7000S device through the TDI input pin. Data is shifted out through the TDO output pin and compared against the expected data.

Programming a pattern into the device requires the following six ISP stages. A stand-alone verification of a programmed pattern involves only stages 1, 2, 5, and 6.

- Enter ISP. The enter ISP stage ensures that the I/O pins transition smoothly from user mode to ISP mode. The enter ISP stage requires 1 ms.
- 2. *Check ID*. Before any program or verify process, the silicon ID is checked. The time required to read this silicon ID is relatively small compared to the overall programming time.
- 3. *Bulk Erase*. Erasing the device in-system involves shifting in the instructions to erase the device and applying one erase pulse of 100 ms.
- Program. Programming the device in-system involves shifting in the address and data and then applying the programming pulse to program the EEPROM cells. This process is repeated for each EEPROM address.
- Verify. Verifying an Altera device in-system involves shifting in addresses, applying the read pulse to verify the EEPROM cells, and shifting out the data for comparison. This process is repeated for each EEPROM address.
- 6. Exit ISP. An exit ISP stage ensures that the I/O pins transition smoothly from ISP mode to user mode. The exit ISP stage requires 1 ms.

## **Programming Times**

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

### Programming a Single MAX 7000S Device

The time required to program a single MAX 7000S device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$

where:  $t_{PROG}$  = Programming time  $t_{PPULSE}$  = Sum of the fixed times to erase, program, and

verify the EEPROM cells

 $Cycle_{PTCK}$  = Number of TCK cycles to program a device

= TCK frequency

The ISP times for a stand-alone verification of a single MAX 7000S device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$

where:  $t_{VER}$  = Verify time

 $t_{VPULSE}$  = Sum of the fixed times to verify the EEPROM cells

 $Cycle_{VTCK}$  = Number of TCK cycles to verify a device

The programming times described in Tables 6 through 8 are associated with the worst-case method using the enhanced ISP algorithm.

Table 6. MAX 7000S t <sub>PU</sub>	able 6. MAX 7000\$ t <sub>PULSE</sub> & Cycle <sub>TCK</sub> Values								
Device	Progra	mming	Stand-Alone Verification						
	t <sub>PPULSE</sub> (s)	Cycle <sub>PTCK</sub>	t <sub>VPULSE</sub> (s)	Cycle <sub>VTCK</sub>					
EPM7032S	4.02	342,000	0.03	200,000					
EPM7064S	4.50	504,000	0.03	308,000					
EPM7128S	5.11	832,000	0.03	528,000					
EPM7160S	5.35	1,001,000	0.03	640,000					
EPM7192S	5.71	1,192,000	0.03	764,000					
EPM7256S	6.43	1,603,000	0.03	1,024,000					

Tables 7 and 8 show the in-system programming and stand alone verification times for several common test clock frequencies.

Table 7. MAX 7000S In-System Programming Times for Different Test Clock Frequencies										
Device		f <sub>TCK</sub>								
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz		
EPM7032S	4.06	4.09	4.19	4.36	4.71	5.73	7.44	10.86	s	
EPM7064S	4.55	4.60	4.76	5.01	5.51	7.02	9.54	14.58	S	
EPM7128S	5.19	5.27	5.52	5.94	6.77	9.27	13.43	21.75	S	
EPM7160S	5.45	5.55	5.85	6.35	7.35	10.35	15.36	25.37	S	
EPM7192S	5.83	5.95	6.30	6.90	8.09	11.67	17.63	29.55	S	
EPM7256S	6.59	6.75	7.23	8.03	9.64	14.45	22.46	38.49	S	

Table 8. MAX	Table 8. MAX 7000S Stand-Alone Verification Times for Different Test Clock Frequencies									
Device		f <sub>TCK</sub>								
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz		
EPM7032S	0.05	0.07	0.13	0.23	0.43	1.03	2.03	4.03	s	
EPM7064S	0.06	0.09	0.18	0.34	0.64	1.57	3.11	6.19	S	
EPM7128S	0.08	0.14	0.29	0.56	1.09	2.67	5.31	10.59	S	
EPM7160S	0.09	0.16	0.35	0.67	1.31	3.23	6.43	12.83	S	
EPM7192S	0.11	0.18	0.41	0.79	1.56	3.85	7.67	15.31	S	
EPM7256S	0.13	0.24	0.54	1.06	2.08	5.15	10.27	20.51	S	

# Programmable Speed/Power Control

MAX 7000 devices offer a power-saving mode that supports low-power operation across user-defined signal paths or the entire device. This feature allows total power dissipation to be reduced by 50% or more, because most logic applications require only a small fraction of all gates to operate at maximum frequency.

The designer can program each individual macrocell in a MAX 7000 device for either high-speed (i.e., with the Turbo Bit<sup>TM</sup> option turned on) or low-power (i.e., with the Turbo Bit option turned off) operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths can operate at reduced power. Macrocells that run at low power incur a nominal timing delay adder ( $t_{LPA}$ ) for the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ , and  $t_{SEXP}$ ,  $t_{ACL}$ , and  $t_{CPPW}$  parameters.

# Output Configuration

MAX 7000 device outputs can be programmed to meet a variety of system-level requirements.

### MultiVolt I/O Interface

MAX 7000 devices—except 44-pin devices—support the MultiVolt I/O interface feature, which allows MAX 7000 devices to interface with systems that have differing supply voltages. The 5.0-V devices in all packages can be set for 3.3-V or 5.0-V I/O pin operation. These devices have one set of VCC pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

The VCCINT pins must always be connected to a 5.0-V power supply. With a 5.0-V  $V_{\rm CCINT}$  level, input voltage thresholds are at TTL levels, and are therefore compatible with both 3.3-V and 5.0-V inputs.

The VCCIO pins can be connected to either a 3.3-V or a 5.0-V power supply, depending on the output requirements. When the VCCIO pins are connected to a 5.0-V supply, the output levels are compatible with 5.0-V systems. When  $V_{\rm CCIO}$  is connected to a 3.3-V supply, the output high is 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with  $V_{\rm CCIO}$  levels lower than 4.75 V incur a nominally greater timing delay of  $t_{\rm OD2}$  instead of  $t_{\rm OD1}$ .

## Open-Drain Output Option (MAX 7000S Devices Only)

MAX 7000S devices provide an optional open-drain (functionally equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired-OR plane.

## **Design Security**

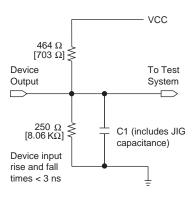
All MAX 7000 devices contain a programmable security bit that controls access to the data programmed into the device. When this bit is programmed, a proprietary design implemented in the device cannot be copied or retrieved. This feature provides a high level of design security because programmed data within EEPROM cells is invisible. The security bit that controls this function, as well as all other programmed data, is reset only when the device is reprogrammed.

## **Generic Testing**

Each MAX 7000 device is functionally tested. Complete testing of each programmable EEPROM bit and all internal logic elements ensures 100% programming yield. AC test measurements are taken under conditions equivalent to those shown in Figure 10. Test patterns can be used and then erased during early stages of the production flow.

### Figure 10. MAX 7000 AC Test Conditions

Power supply transients can affect AC measurements. Simultaneous transitions of multiple outputs should be avoided for accurate measurement. Threshold tests must not be performed under AC conditions. Large-amplitude, fast ground-current transients normally occur as the device outputs discharge the load capacitances. When these transients flow through the parasitic inductance between the device ground pin and the test system ground. significant reductions in observable noise immunity can result. Numbers in brackets are for 2.5-V devices and outputs. Numbers without brackets are for 3.3-V devices and outputs.



# QFP Carrier & Development Socket

MAX 7000 and MAX 7000E devices in QFP packages with 100 or more pins are shipped in special plastic carriers to protect the QFP leads. The carrier is used with a prototype development socket and special programming hardware available from Altera. This carrier technology makes it possible to program, test, erase, and reprogram a device without exposing the leads to mechanical stress.



For detailed information and carrier dimensions, refer to the *QFP Carrier* & *Development Socket Data Sheet*.



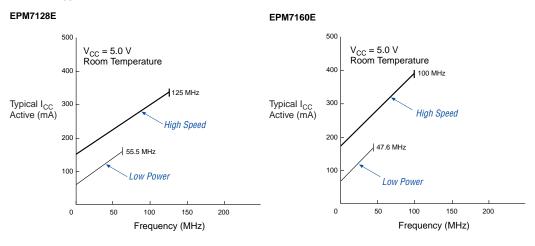
MAX 7000S devices are not shipped in carriers.

Table 2	5. MAX 7000 & MAX 7000E	External Timing I	Paramete	ers /	lote (1)				
Symbol	Parameter	Conditions	Speed Grade						
			-15		-15T		-20		
			Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t <sub>SU</sub>	Global clock setup time		11.0		11.0		12.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input	(2)	3.0		-		5.0		ns
t <sub>FH</sub>	Global clock hold time of fast input	(2)	0.0		-		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		8.0		8.0		12.0	ns
t <sub>CH</sub>	Global clock high time		5.0		6.0		6.0		ns
t <sub>CL</sub>	Global clock low time		5.0		6.0		6.0		ns
t <sub>ASU</sub>	Array clock setup time		4.0		4.0		5.0		ns
t <sub>AH</sub>	Array clock hold time		4.0		4.0		5.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		15.0		15.0		20.0	ns
t <sub>ACH</sub>	Array clock high time		6.0		6.5		8.0		ns
t <sub>ACL</sub>	Array clock low time		6.0		6.5		8.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(3)	6.0		6.5		8.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			13.0		13.0		16.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(5)	76.9		76.9		62.5		MHz
t <sub>ACNT</sub>	Minimum array clock period			13.0		13.0		16.0	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(5)	76.9		76.9		62.5		MHz
f <sub>MAX</sub>	Maximum clock frequency	(6)	100		83.3	_	83.3	_	MHz

Symbol	Parameter	Conditions	Speed Grade						
			-	-15		5T	-20		
			Min	Max	Min	Max	Min	Max	x
t <sub>IN</sub>	Input pad and buffer delay			2.0		2.0		3.0	ns
t <sub>IO</sub>	I/O input pad and buffer delay			2.0		2.0		3.0	ns
t <sub>FIN</sub>	Fast input delay	(2)		2.0		_		4.0	ns
t <sub>SEXP</sub>	Shared expander delay			8.0		10.0		9.0	ns
t <sub>PEXP</sub>	Parallel expander delay			1.0		1.0		2.0	ns
t <sub>LAD</sub>	Logic array delay			6.0		6.0		8.0	ns
t <sub>LAC</sub>	Logic control array delay			6.0		6.0		8.0	ns
t <sub>IOE</sub>	Internal output enable delay	(2)		3.0		_		4.0	ns
t <sub>OD1</sub>	Output buffer and pad delay Slow slew rate = off V <sub>CCIO</sub> = 5.0 V	C1 = 35 pF		4.0		4.0		5.0	ns
t <sub>OD2</sub>	Output buffer and pad delay Slow slew rate = off V <sub>CCIO</sub> = 3.3 V	C1 = 35 pF (7)		5.0		-		6.0	ns
t <sub>OD3</sub>	Output buffer and pad delay Slow slew rate = on V <sub>CCIO</sub> = 5.0 V or 3.3 V	C1 = 35 pF (2)		8.0		-		9.0	ns
t <sub>ZX1</sub>	Output buffer enable delay Slow slew rate = off V <sub>CCIO</sub> = 5.0 V	C1 = 35 pF		6.0		6.0		10.0	ns
t <sub>ZX2</sub>	Output buffer enable delay Slow slew rate = off V <sub>CCIO</sub> = 3.3 V	C1 = 35 pF (7)		7.0		-		11.0	ns
t <sub>ZX3</sub>	Output buffer enable delay Slow slew rate = on V <sub>CCIO</sub> = 5.0 V or 3.3 V	C1 = 35 pF (2)		10.0		-		14.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		6.0		6.0		10.0	ns
t <sub>SU</sub>	Register setup time		4.0		4.0		4.0		ns
t <sub>H</sub>	Register hold time		4.0		4.0		5.0		ns
t <sub>FSU</sub>	Register setup time of fast input	(2)	2.0		_	İ	4.0		ns
t <sub>FH</sub>	Register hold time of fast input	(2)	2.0		-		3.0		ns
t <sub>RD</sub>	Register delay			1.0		1.0		1.0	ns
t <sub>COMB</sub>	Combinatorial delay			1.0		1.0		1.0	ns
t <sub>IC</sub>	Array clock delay			6.0		6.0		8.0	ns
t <sub>EN</sub>	Register enable time			6.0		6.0		8.0	ns
t <sub>GLOB</sub>	Global control delay			1.0		1.0		3.0	ns
t <sub>PRE</sub>	Register preset time			4.0		4.0		4.0	ns
t <sub>CLR</sub>	Register clear time			4.0		4.0		4.0	ns
t <sub>PIA</sub>	PIA delay			2.0		2.0		3.0	ns
t <sub>LPA</sub>	Low-power adder	(8)		13.0		15.0		15.0	ns

Symbol	Parameter	Conditions	Speed Grade						
			-	-7		-10		-15	
			Min	Max	Min	Max	Min	Max	1
t <sub>IN</sub>	Input pad and buffer delay			0.3		0.5		2.0	ns
t <sub>IO</sub>	I/O input pad and buffer delay			0.3		0.5		2.0	ns
t <sub>FIN</sub>	Fast input delay			3.4		1.0		2.0	ns
t <sub>SEXP</sub>	Shared expander delay			3.9		5.0		8.0	ns
$t_{PEXP}$	Parallel expander delay			1.1		0.8		1.0	ns
$t_{LAD}$	Logic array delay			2.6		5.0		6.0	ns
t <sub>LAC</sub>	Logic control array delay			2.6		5.0		6.0	ns
t <sub>IOE</sub>	Internal output enable delay			0.8		2.0		3.0	ns
t <sub>OD1</sub>	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns
t <sub>OD2</sub>	Output buffer and pad delay	C1 = 35 pF (6)		1.0		2.0		5.0	ns
t <sub>OD3</sub>	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		8.0	ns
t <sub>ZX1</sub>	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns
t <sub>ZX2</sub>	Output buffer enable delay	C1 = 35 pF (6)		4.5		5.5		7.0	ns
t <sub>ZX3</sub>	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns
t <sub>SU</sub>	Register setup time		1.1		2.0		4.0		ns
t <sub>H</sub>	Register hold time		1.6		3.0		4.0		ns
t <sub>FSU</sub>	Register setup time of fast input		2.4		3.0		2.0		ns
t <sub>FH</sub>	Register hold time of fast input		0.6		0.5		1.0		ns
$t_{RD}$	Register delay			1.1		2.0		1.0	ns
t <sub>COMB</sub>	Combinatorial delay			1.1		2.0		1.0	ns
t <sub>IC</sub>	Array clock delay			2.9		5.0		6.0	ns
$t_{EN}$	Register enable time			2.6		5.0		6.0	ns
t <sub>GLOB</sub>	Global control delay			2.8		1.0		1.0	ns
t <sub>PRE</sub>	Register preset time			2.7		3.0		4.0	ns
t <sub>CLR</sub>	Register clear time			2.7		3.0		4.0	ns
t <sub>PIA</sub>	PIA delay	(7)		3.0		1.0		2.0	ns
t <sub>LPA</sub>	Low-power adder	(8)		10.0	İ	11.0		13.0	ns

Figure 14. I<sub>CC</sub> vs. Frequency for MAX 7000 Devices (Part 2 of 2)



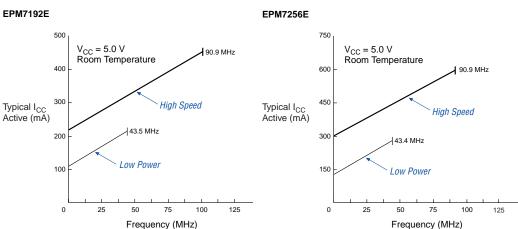
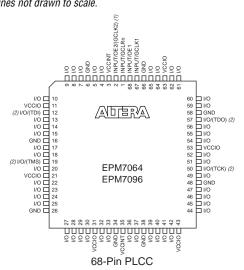


Figure 17. 68-Pin Package Pin-Out Diagram

Package outlines not drawn to scale.

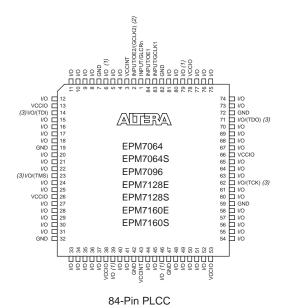


#### Notes:

- The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.

#### Figure 18. 84-Pin Package Pin-Out Diagram

Package outline not drawn to scale.

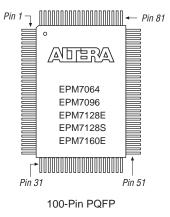


#### Notes:

- (1) Pins 6, 39, 46, and 79 are no-connect (N.C.) pins on EPM7096, EPM7160E, and EPM7160S devices.
- (2) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (3) JTAG ports are available in MAX 7000S devices only.

Figure 19. 100-Pin Package Pin-Out Diagram

Package outline not drawn to scale.



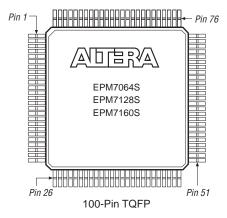
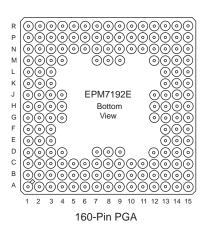
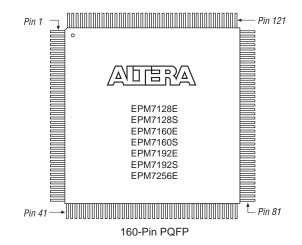


Figure 20. 160-Pin Package Pin-Out Diagram

Package outline not drawn to scale.









101 Innovation Drive San Jose, CA 95134 (408) 544-7000 www.altera.com Applications Hotline: (800) 800-EPLD Literature Services: literature@altera.com Copyright © 2005 Altera Corporation. All rights reserved. Altera, The Programmable Solutions Company, the stylized Altera logo, specific device designations, and all other words and logos that are identified as trademarks and/or service marks are, unless noted otherwise, the trademarks and service marks of Altera Corporation in the U.S. and other countries. All other product or service names are the property of their respective holders. Altera products are protected under numerous U.S. and foreign patents and pending applications, maskwork rights, and copyrights. Altera warrants performance of its semiconductor products to current specifications in accordance with Altera's standard warranty, but reserves the right to make changes to any products and services at any time without notice. Altera assumes no responsibility or liability arising out of the application or use of any information, product, or service described herein except as expressly agreed to in writing by Altera Corporation. Altera customers are advised to obtain the latest version of device specifications before relying on any published information and before placing orders for products or services.

I.S. EN ISO 9001